

Reduction of Boride Enhanced Diffusion in Silicon by High Energy Si Implantation*

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We demonstrated that implantation of MeV Si ions into a Si substrate can significantly reduce boride-enhanced diffusion associated with a high B concentration layer. Anomalous profile spreading caused by transient enhanced diffusion¹ (TED) and boride-enhanced diffusion² (BED) hampers the formation of ultra shallow p^+/n junctions for the next generation silicon technology. It has been demonstrated that BED exists in the proximity of a silicon layer containing a high concentration of B.² BED is attributed to a silicon boride phase which injects Si interstitials during annealing. It is extremely difficult to avoid the formation of the boride phase since a high boron concentration is needed in the processing of a ultra shallow p^+ layer.

Inspired by Venezia *et al.*³ using a superlattice structure for diffusion studies, we used similar sample configurations. In this study, a molecular-beam-epitaxy grown Si layer with a B concentration of $10^{21}/\text{cm}^3$ over a 10 nm region capped with 100 nm Si was used as a source of boride-enhanced diffusion. A sequence of four B delta-doped layers with 100 nm Si spacers was grown prior to the source layer to monitor the diffusion. Half of the sample was implanted with 1 MeV Si ions at a dose of $10^{16}/\text{cm}^2$, followed by annealing at 800 °C, 900 °C and 1000 °C for different periods of time. For control samples without the MeV Si implant, boride-enhanced diffusion was observed while the MeV Si-implanted sample showed reduced diffusion, with boride-enhanced diffusion completely suppressed at 900 °C.

References:

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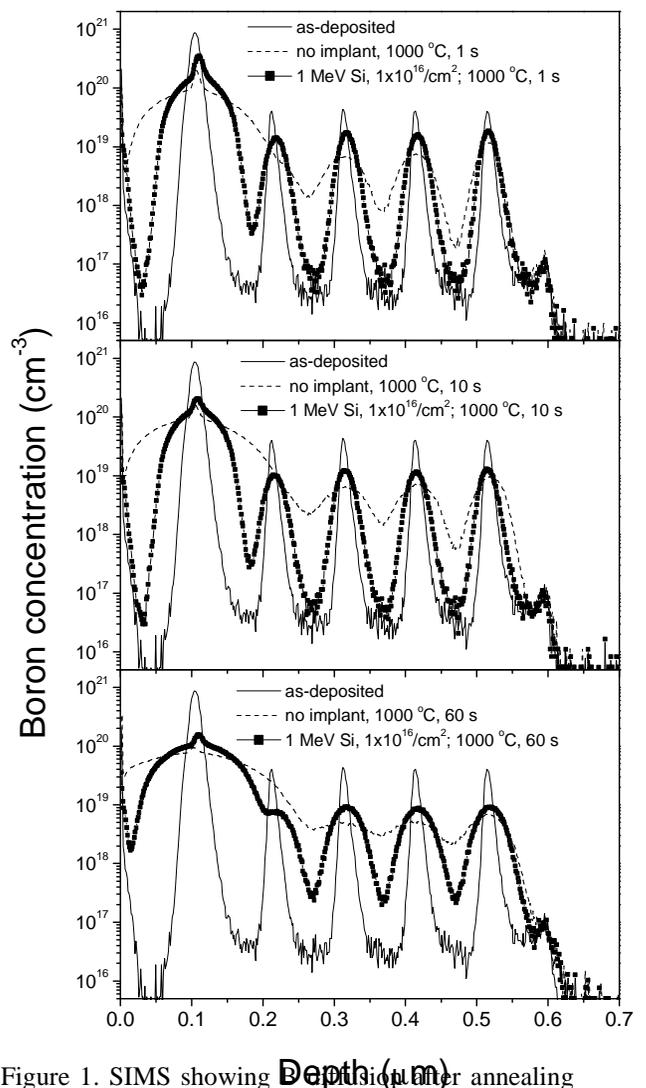


Figure 1. SIMS showing Boron concentration after annealing at 1000 °C for periods of 1s, 10s and 60s. Samples with 1 MeV $10^{16}/\text{cm}^2$ Si^+ implant (the squares) show suppressed diffusions in comparison with non-implanted one (the dash lines).